

Amendments to the Claims

1. **(Currently Amended)** A wafer support plate for supporting a semiconductor wafer, comprising:

a support surface on which ~~a~~ the semiconductor wafer is to be supported; and
a crystal orientation mark which indicates a crystal orientation of the supported semiconductor wafer.

2. **(Original)** A wafer support plate according to claim 1, wherein said crystal orientation mark is formed at an outer-peripheral part of said support surface.

3. **(Original)** A wafer support plate according to claim 1, wherein said crystal orientation mark is formed on an outer-peripheral side surface of said support surface.

4. **(Currently Amended)** A wafer support plate according to claim 1, wherein said crystal orientation mark is formed as a cut-out notch of ~~by cutting away~~ an outer-peripheral part of said support surface.

5. **(Previously Presented)** A wafer support plate according to claim 1, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

6. **(Previously Presented)** A wafer support plate according to claim 2, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

7. **(Previously Presented)** A wafer support plate according to claim 3, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

8. **(Previously Presented)** A wafer support plate according to claim 4, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

9. **(New)** A semiconductor wafer arrangement including:
a semiconductor wafer; and
a wafer support plate comprising
a support surface on which said semiconductor wafer is supported, and
a crystal orientation mark which indicates a crystal orientation of said supported semiconductor wafer.

10. **(New)** A semiconductor wafer arrangement according to claim 9, wherein said crystal orientation mark is formed at an outer-peripheral part of said support surface.

11. **(New)** A semiconductor wafer arrangement according to claim 9, wherein said crystal orientation mark is formed on an outer-peripheral side surface of said support surface.

12. **(New)** A semiconductor wafer arrangement according to claim 9, wherein said crystal orientation mark is formed as a cut-out notch of an outer-peripheral part of said support surface.

13. **(New)** A semiconductor wafer arrangement according to claim 9, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

14. **(New)** A semiconductor wafer arrangement according to claim 10, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

15. **(New)** A semiconductor wafer arrangement according to claim 11, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.

16. **(New)** A semiconductor wafer arrangement according to claim 12, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.